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Singapore

UTAC completes acquisition of Singapore Wafer Bumping Assets from Powertech Technology (Singapore) Pte. Ltd.

UTAC Holdings Ltd. announced today that its affiliate (“UTAC” or “the Company”) has completed its purchase of the Singapore wafer bumping assets from Powertech Technology (Singapore) Pte. Ltd. (“PTI Singapore”).

As part of the transaction, UTAC has entered into several ancillary agreements including a Transitional Services Agreement and License Agreement with Powertech Technology Inc. to enable a seamless transition of the wafer bumping related operations to UTAC. In addition, all members of the PTI Singapore wafer bumping team are joining UTAC.

“With the completion of this transaction, UTAC can provide advanced 300mm wafer bumping capabilities and technology. It complements our world-class wafer probe and back-end WLCSP capabilities within the island,” said Dr. John Nelson, Chief Executive Officer of UTAC. This new capability enables UTAC to provide full turn-key WLCSP services in Singapore to all our customers. We welcome the PTI Singapore wafer bumping employees to the UTAC family.



About UTAC Holdings Ltd

UTAC Holdings Ltd (UTAC) is a leading independent provider of assembly and test services for a broad range of semiconductor chips and we offer a full range of semiconductor assembly and test services in the following key product categories: analog, mixed-signal and logic, and memory. Our customers are primarily fabless companies, integrated device manufacturers and wafer foundries. UTAC is headquartered in Singapore, with production facilities located in Singapore, Thailand, China, Indonesia and Malaysia, in addition to its global sales network focused on five regions: United States, Japan, China, rest of Asia and Europe, with sales offices located in each of these regions.